

IN THE SPECIFICATION

Please amend the specification as follows.

The paragraph beginning at page 3, line 1, is amended as follows:

The coolant is typically transferred through an expansion valve before the coolant enters the evaporator. The expansion valve reduces the pressure of the coolant and also reduces the temperature to enhance the efficiency of the cooling system and allow for coolant temperatures that are different from [[than]] what otherwise would normally be available.

The paragraph beginning at page 6, line 16, is amended as follows:

Once the evaporator 14 begins cooling the processor 34, the control 24 either turns off the heater 22 or uses the heater 22 to maintain the liquid coolant 30 at an optimum temperature for evaporation by the evaporator 14. The control 24 may also utilize a timer that turns off the heater 22 and or the electronic device after a certain period of time. The control 24 may also comprise a temperature sensor that indicates when the processor is inactive. During an extended period of inactivity, the control 24 may shut down the heater 22. In addition, the temperature sensor may detect when the processor 34 is operating at a dangerously high temperature. When the control 24 detects that the processor is operating at too high [[of]] a temperature, the control 24 [[to]] shuts down the electronic device before the processor 34 is damaged.

The paragraph beginning at page 8, line 9, is amended as follows:

The example embodiments described above are not shown in a system chassis. However, a processor cooling system according to any of the example embodiments described above may be incorporated into a well known [[know]] computerized system including a chassis, an integrated circuit board mounted in the chassis, and one or more processors coupled to the integrated circuit board.

The paragraph beginning at page 8, line 27, is amended as follows:

Another embodiment of the present invention relates to a kit of parts for an electronic device cooling system. The kit may comprise any combination of one or more (i) evaporators 14 that are adapted to be thermally connected to the electronic device such that the evaporator 14 removes thermal energy from the electronic device by evaporating a liquid coolant; (ii) condensers 18 that are adapted to be connected to the evaporators 14 such that the condensers 18 condense the coolant 30 that is evaporated by the evaporators 14; and (iii) heaters 22 that are adapted to add thermal energy to the liquid coolant 30 before the liquid coolant 30 is evaporated by the evaporator 14. The kit may also comprise one or more flexible conduits 26A, 26B that are adapted to be coupled to the condenser 18 and the evaporator 14 in order to guide the coolant 30 between any condenser 18 and any evaporator 14. In addition, the kit may include one or more pumps (not shown) that are adapted to transport the coolant 30 from the evaporator 14 to the condenser 18.